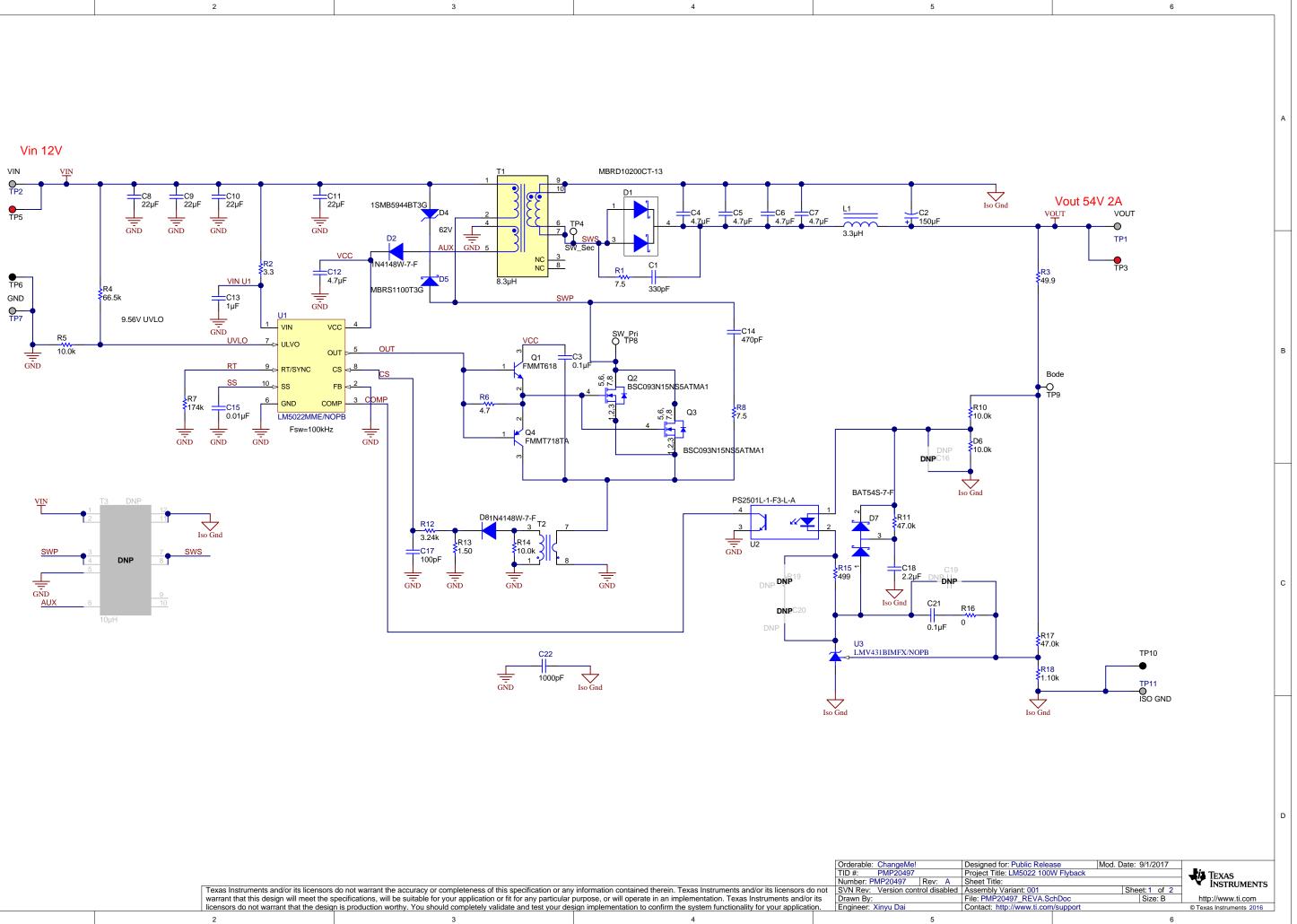
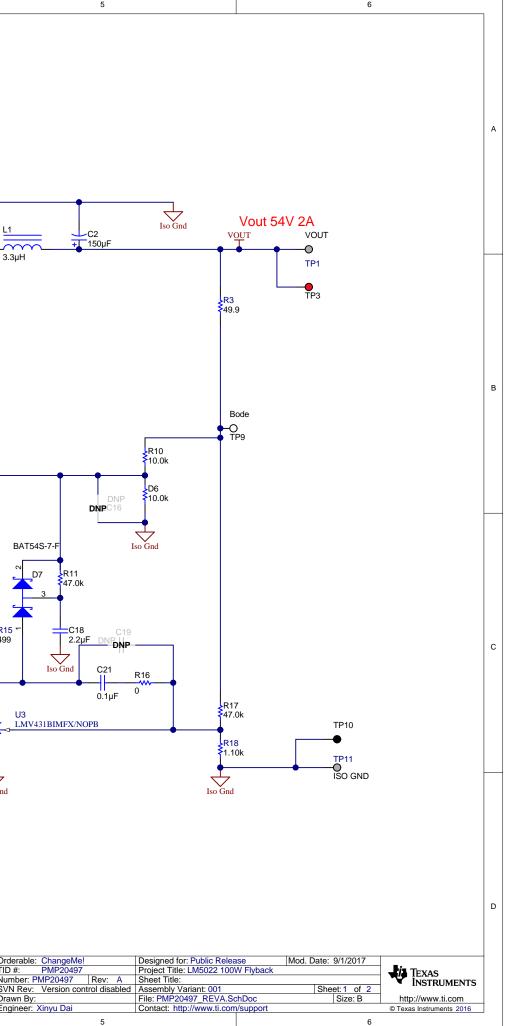
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licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.	Eng

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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH NY PMS 440 0025 PH

DNP FID1 DNP DNP



PCB LOGO FCC disclaimer

Variant/Label Table			
Variant Label Text			
001			

ZZ1 Label Assembly Note This Assembly Note is for PCB labels only

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ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: ChangeMel TID #: PMP20497 Number: PMP20497 SVN Rev: Version cor Drawn By: Engineer: Xinyu Dai

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licensors do not warrant that the desig	n is production worthy. You should completely validate and test your des	sign implementation to confirm the system functionality for your applicatio	n. Engir
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Project Title: LM5022 100\	N Flyback		TEXAS
Sheet Title:			TEXAS INSTRUMENTS
Assembly Variant: 001		Sheet: 2 of 2	INSTITUTIENTS
File: PMP20497_REVA_H	ardware.SchDoc	Size: B	http://www.ti.com
Contact: http://www.ti.com/support		© Texas Instruments 2016	
		6	
	Project Title: LM5022 100 Sheet Title: Assembly Variant: 001 File: PMP20497_REVA_H	Project Title: LM5022 100W Flyback Sheet Title: Assembly Variant: 001 File: PMP20497_REVA_Hardware.SchDoc	Project Title: LM5022 100W Flyback Sheet Title: Assembly Variant: 001 Sheet: 2 of 2 File: PMP20497_REVA_Hardware.SchDoc Size: B

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